100% Material Declaration Data Sheet for Zynq®-7000 RB484 Package

PK682 (v1.0) Oct 31, 2014

Average Weight: 5.5549 g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					**0.156648**	**2.820%**
	Silicon	7440-21-3	100.00	Basis	0.156648	
Solder Bump					**0.007775**	**0.140%**
	Tin	7440-31-5	63.00	Basis	0.004898	
	Lead	7439-92-1	37.00	Basis	0.002877	
Underfill					**0.027300**	**0.491%**
	Bisphenol F/ Epichlorohydrin	9003-36-5	20.00	Basis	0.005460	
	Phenolic Resin	Trade Secret	15.00	Basis	0.004095	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.00	Basis	0.001365	
	Amine type accelerator	Trade Secret	5.00	Basis	0.001365	
	Silicon Dioxide	60676-86-0	51.50	Basis	0.014060	
	Carbon Black	1333-86-4	1.00	Basis	0.000273	
	Additives	Trade Secret	2.50	Additive	0.000683	
Solder Paste					**0.004664**	**0.084%**
	Tin	7440-31-5	63.00	Metal	0.002938	
	Lead	7439-92-1	37.00	Metal	0.001726	
Capacitor 1					**0.000600**	**0.011%**
	Barium	12047-27-7	71.29	Ceramic	0.000428	
	Manganese	1313-13-9	10.43	Ceramic	0.000063	
	Nickel	7440-02-0	2.00	Internal Electrode	0.000012	
	Copper	7440-50-8	11.57	Termination	0.000069	
	Glass oxide	65997-17-3	0.21	Termination	0.000001	
	Nickel	7440-02-0	1.80	Plating	0.000011	
	Gold	7440-57-5	2.70	Plating	0.000016	

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Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Capacitor 2					**0.004650**	**0.084%**
	Barium	12047-27-7	72.40	Ceramic	0.003367	
	Manganese	1313-13-9	10.60	Ceramic	0.000493	
	Nickel	7440-02-0	4.00	Internal Electrode	0.000186	
	Copper	7440-50-8	5.80	Termination	0.00027	
	Glass Oxide	65997-17-3	0.20	Termination	0.000009	
	Nickel	7440-02-0	2.66	Plating	0.000124	
	Tin	7440-31-5	3.99	Plating	0.000186	
	Lead	7439-92-1	0.35	Plating	0.000016	
Capacitor 3					**0.014400**	**0.259%**
	Barium	12047-27-7	88.86	Ceramic	0.012795	
	Manganese	1313-13-9	1.43	Ceramic	0.000206	
	Nickel	7440-02-0	4.29	Internal Electrode	0.000617	
	Copper	7440-50-8	0.70	Termination	0.000101	
	Glass oxide	65997-17-3	0.01	Termination	0.000002	
	Nickel	7440-02-0	3.57	Plating	0.000514	
	Tin	7440-31-5	0.90	Plating	0.00013	
	Lead	7439-92-1	0.24	Plating	0.000035	
Heat Sink					**3.464000**	**62.359%**
	Copper	7440-50-8	97.94	Main Material	3.392642	
	Nickel	8049-31-8	2.06	Main Material	0.071358	
Heat Sink Adhesive					**0.057200**	**1.030%**
	Aluminium Oxide Al203	1344-28-1	70.00	Main Material	0.040040	
	Dimethyl siloxane, dimethylvinyl-terminated	68083-19-2	30.00	Main Material	0.017160	
Solder Ball					**0.460670**	**8.293%**
	Tin	7440-31-5	63.00	Main Material	0.290222	
	Lead	7439-92-1	37.00	Main Material	0.170448	
Substrate					**1.357000**	**24.429%**
	Copper	7440-50-8	36.77		0.498997	
	Tin	7440-31-5	0.81		0.010962	
	Lead	7439-92-1	0.47		0.006438	
	BT Core	Trade Secret	48.22		0.654317	
	ABF	Trade Secret	11.26		0.152754	
	Solder Mask	Trade Secret	2.47		0.033531	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
10/31/2014	1.0	Xilinx Initial Release

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